RELIABILITY REPORT

FOR

MAX352ESE+

PLASTIC ENCAPSULATED DEVICES

April 26, 2013

MAXIM INTEGRATED

160 RIO ROBLES

SAN JOSE, CA 95134

Approved by
Sokhom Chum
Quality Assurance
Reliability Engineer

Conclusion

The MAX352ESE+ successfully meets the quality and reliability standards required of all Maxim Integrated products. In addition, Maxim Integrated's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim Integrated's quality and reliability standards.

Table of Contents

I. Device Description

A. General

The MAX351/MAX352/MAX353 are precision, quad, single-pole single-throw (SPST) analog switches. The MAX351 has four normally closed (NC), and the MAX352 has four normally open (NO) switches. The MAX353 has two NO and two NC switches. All three parts offer low on resistance (less than 35), guaranteed to match within 2 between channels and to remain flat over the analog signal range (3 max). They also offer low leakage (less than 250pA at +25°C and less than 6nA at +85°C) and fast switching (turn-on time less than 175ns and turn-off time less than 145ns). The MAX351/MAX352/MAX353 are fabricated with Maxim's new improved 44V silicon-gate process. Design improvements guarantee extremely low charge injection (10pC), low power consumption (35µW), and electrostatic discharge (ESD) greater than 2000V. The 44V maximum breakdown voltage allows rail-to-rail analog signal handling. These monolithic switches operate with a single positive supply (+10V to +30V) or with split supplies (±4.5V to ±20V) while retaining CMOS-logic input compatibility and fast switching. CMOS inputs provide reduced input loading.

II. Manufacturing Information

A. Description/Function:	Precision, Quad, SPST Analog Switches
B. Process:	S5
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Malaysia, Thailand, or Philippines
F. Date of Initial Production:	Pre 1997

III. Packaging Information

A. Package Type:	16-pin SOIC (N)
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-0301-0596
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	115°C/W
K. Single Layer Theta Jc:	32°C/W
L. Multi Layer Theta Ja:	82.2°C/W
M. Multi Layer Theta Jc:	32°C/W

IV. Die Information

A. Dimensions:	80 X 97 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	5.0 microns (as drawn)
F. Minimum Metal Spacing:	5.0 microns (as drawn)
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Richard Aburano (Manager, Reliability Engineering) Don Lipps (Manager, Reliability Engineering) Bryan Preeshl (Vice President of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{1000 \times 4340 \times 393 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 0.5 \times 10^{-9}$

λ = 0.5 F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim Integrated's reliability monitor program. Maxim Integrated performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maximintegrated.com/qa/reliability/monitor. Cumulative monitor data for the S5 Process results in a FIT Rate of 0.09 @ 25C and 1.53 @ 55C (0.8 eV, 60% UCL).

B. E.S.D. and Latch-Up Testing (ESD lot XRLBDQ002A D/C 9344, Latch-Up lot NRLBFQ003D D/C 9930)

The AG38-1 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2000V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250mA.

Table 1

Reliability Evaluation Test Results

MAX352ESE+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)					
	Ta = 135°C	DC Parameters	80	0	NRLCGA367A, D/C 0735
	Biased	& functionality	80	0	NRLCGA370C, D/C 0735
	Time = 1000 hrs.		76	0	NRLAFA130C, D/C 0343
			77	0	NRLAFA109G, D/C 0308
			80	0	NRLAFA095J, D/C 0203

Note 1: Life Test Data may represent plastic DIP qualification lots.